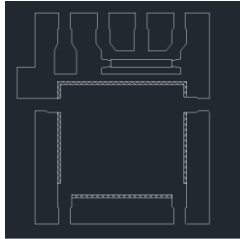
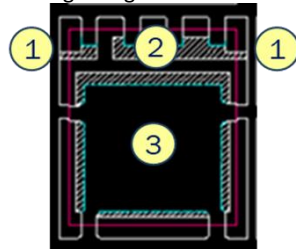
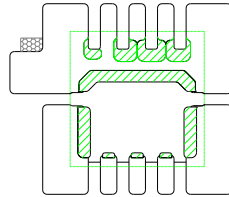
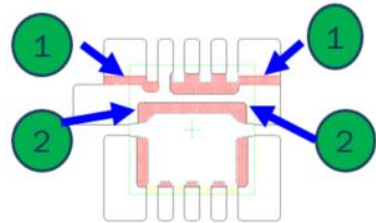




Title of Change:	Wafer Fab Transfer for Trench 6 MOSFET Technology to Global Foundries in New York, US.
Proposed Changed Material First Ship Date:	08 Jan 2022 or earlier if approved by customer
Current Material Last Order Date:	27 Nov 2021 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	07 Jan 2022 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Discrete components
Contact information:	Contact your local ON Semiconductor Sales Office or Ammar.Anuar@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com> . Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	01 Jan 2021
PPAP Availability Date:	01 Jan 2021
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Robert.Baran@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Packing/Shipping	Dry pack requirements change
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change in process technology (plating...), Change of specified assembly process sequence (deletion and/or additional process step)
Description and Purpose:	
<p>This Product Change Notification, is the continuation from IPCN22966ZD, which is intended to increase capacity for ON's automotive 30V and 40V Trench 6 MOSFET technology products by transferring wafer fabrication for these products to the Global Foundries Fab located in New York, US.</p> <p>The changes include transferring wafer fabrication, back grind and back metal, to Global Foundries, and utilizing 300mm instead of 200mm diameter wafers. And while the assembly location remains unchanged (at ON Semiconductor, Seremban, Malaysia), wafer saw and die attach tooling are being updated to accommodate 300mm wafers. In addition, the Wetable Flank leadframe design and plating process are being enhanced, as tabulated below, in order to improve the sidewall plating and the elimination of Dry Pack.</p>	

There is no change to the orderable part number.

There is no product marking change as a result of this change.

	Before Change	After Change
Wafer Fabrication Site	ON Aizu, Japan ON Gresham, US	<u>Global Foundries, US</u>
Wafer Diameter	200mm (existing sites)	300mm (Global Foundries)
Wafer Probe Site	ON Seremban, Malaysia	<u>Global Foundries, US</u>
Back Grind, Back Metal Site	ON ISMF, Malaysia	<u>Global Foundries, US</u>
Wettable Flank Plating Site	Metek, Malaysia (Sub-con)	ON Seremban, Malaysia
S08FL Lead Frame design	<ol style="list-style-type: none"> No tie bar connect to the gate and source lead Upset lead design Standard flag size 	<ol style="list-style-type: none"> Additional tie bar connect to gate and source lead Flat lead design Larger flag size 
S08FL Case Outline	488AA	507BA
S08FL Dimension "L1" in case outline	0.125mm	0.15mm
u8FL Lead Frame design	<ol style="list-style-type: none"> No tie bar connect to the gate and source lead Chamfer flag. 	<ol style="list-style-type: none"> Additional tie bar connect to gate and source lead Removed chamfer 
u8FL Case Outline	511AB	515AN
u8FL Dimension "L" in case outline	0.30mm – 0.56mm	0.30mm – 0.59mm
Sidewall Plating Method	Electroless SN plating	Electrolytic SN plating
Packing	Drypack (MSL 1)	No Drypack (MSL 1)

Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	<p>The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p>



Sites Affected:				
ON Semiconductor Sites		External Foundry/Subcon Sites		
On Semiconductor Gresham, United States		GlobalFoundries, Fab 10, New York, US		
ON Semiconductor Aizu, Japan		Metek Seremban, Malaysia (Subcon)		
ON Semiconductor Seremban, Malaysia				
ON ISMF, Malaysia				
Marking of Parts/ Traceability of Change:		Material will be traceable with ONs lot trace code & tracking		
Reliability Data Summary:				
QV DEVICE NAME(DIE QUAL) : NVMF55C404NL				
RMS : 66099, 67744, 67566, 67567				
PACKAGE : SO8FL-HE				
Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=175°C, 100% max rated Vds	2016 hrs	0/231
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	2016 hrs	0/231
HTSL	JESD22-A103	Ta= 175°C	2016 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off =2 min	30000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260°C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
QV DEVICE NAME(DIE QUAL) : NVMF55C404N				
RMS : 66100				
PACKAGE : SO8FL-HE				
Test	Specification	Condition	Interval	Results
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	2016 hrs	0/231
QV DEVICE NAME (PACKAGE QUAL) : NVMF55C404N				
RMS : 68528, 68531				
PACKAGE : SO8FL-HE				
Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta = 150 °C	1008 hrs	0/84
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/80
HTRB	JESD22-A108	Ta=150°C, 100% max rated Vds	1008 hrs	0/84
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	2016 hrs	0/84
TC+PC	JESD22-A104	Ta = -65°C to +150°C	1000 cyc	0/84
IOL+PC	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=100°C max, Ton = Toff = 2min	30000 cyc	0/84
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/504
RSH	JESD22-B106	Ta = 265°C, 10 sec		0/15
SD	JSTD002	Ta = 245°C, 10 sec		0/15



QV DEVICE NAME (PACKAGE QUAL) : NVTFS6H850N
 RMS : 64634,65635,65199,64753,66669
 PACKAGE : u8FL

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta = 175 °C	2016 hrs	0/231
HAST	JESD22 A110	130°C/85% RH ~18.8 psig, bias = 80% of rated V or up to maximum 100V	192 hrs	0/231
TC+PC	JESD22-A104	Ta = -55°C to +150°C	1000 cyc	0/231
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
IOL+PC	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=100°C max, Ton = Toff = 2min	30000 cyc	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/924
RSH	JESD22-B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45

Note AEC-1 pager is attached.

To view attachments:

- 1.Download pdf copy of the PCN to your computer
- 2.Open the downloaded pdf copy of the PCN
- 3.Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4.Then click on the attached file/s

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NVMF55C404NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C423NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG



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NVMF55C456NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C01NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C01NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C03NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C03NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C05NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C302NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C410NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C423NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C423NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C423NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C426NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C426NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C426NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG



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NVMF55C426NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C430NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C442NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG



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NVTFS4C05NWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS4C13NWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS4C13NWFTWG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS5C453NLWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS5C466NLWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG

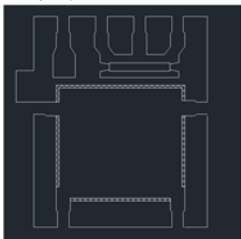
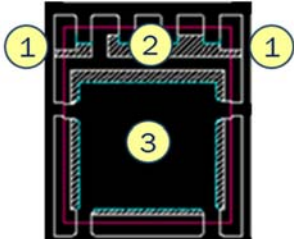
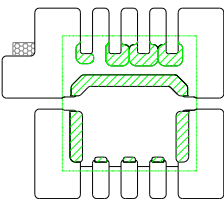
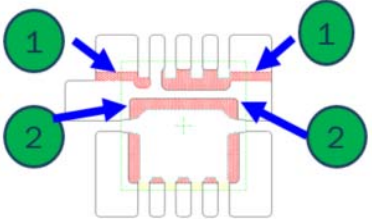
Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



変更件名:	グローバルファンドリー(ニューヨーク、米国)にて Trench 6 MOSFET テクノロジー製品のウェハー工場生産能力拡大
初回出荷予定日:	08 Jan 2022 またはお客様からの承認が得られた場合はそれ以前。
現在の材料の最終注文日:	27 Nov 2021 既存品の最終注文日以降の注文は、この PCN に記載されている変更後品の注文とみなされます。この日付より後の既存品(変更前品)の注文は、相互契約により変更前品の在庫状況に応じて履行されます。
現在の材料の最終出荷日:	07 Jan 2022 既存品(変更前品)の最終出荷日は、変更前品の製造および在庫の状況によって変更されることがあります。
製品カテゴリ:	アクティブなコンポーネント - 個別コンポーネント
連絡先情報:	現地のオン・セミコンダクター営業所または Ammar.Anuar@onsemi.com にお問い合わせください。
サンプル:	現地のオン・セミコンダクター営業所に注文するか、また PCN.samples@onsemi.com にお問い合わせください。 サンプルは、この変更通知の発行から 45 日以内に要求してください。 サンプル納入時は、依頼日、数量、特別梱包材/ラベル条件によって異なります。
追加の信頼性データ:	お客さまの地域のオン・セミコンダクター営業所または Robert.Baran@onsemi.com にお問い合わせください。
サンプル提供開始可能日:	01 Jan 2021
PPAP 提供開始日:	01 Jan 2021
追加の信頼性データ:	お客さまの地域のオン・セミコンダクター営業所または Robert.Baran@onsemi.com にお問い合わせください。
通知種別:	これは、お客様宛の最終製品 / プロセス変更通知 (FPCN) です。 FPCN は、変更実施の 12 か月前、またはお客様からの承認が得られた場合はそれ以前に発行されることがあります。 オン・セミコンダクターは、この通知の送付から 45 日以内に書面による問い合わせが行われないうちに、この変更希望およびその条件が受諾されたものとみなします。お問い合わせは、 PCN.Support@onsemi.com をお願いします。
変更カテゴリ:	変更種別
梱包/出荷	ドライ パック要件の変更
プロセス-ウェーハ製造	ウェハー工場の全て／一部の異なる場所/拠点/外注への移管 新規ウェハー径
テストフロー	電氣的ウェハー検査の全て／一部または最終検査(あるいはその両方)を異なる場所／拠点／外注へ移管
プロセス - 組立	組立の全て／一部の異なる場所／拠点／外注への移管 プロセステクノロジー (メッキ...), 指定の組立プロセス順序の変更(プロセス手順の削除または追加)
説明および目的:	<p>本製品変更通知は、IPC22966ZD からの続きであり、オンの車載用 30V および 40V Trench 6 MOSFET テクノロジー製品のウェハー製造を、米国ニューヨーク州にあるグローバルファンドリー工場に移管することにより、生産能力の拡大を図ることを目的としています。</p> <p>変更は、ウェハー製造、バックグランドおよびバックメタルのグローバルファウンドリーへの移管、そして 200mm ではなく 300mm 径のウェハーの使用が含まれます。また、組立拠点は変更されませんが(オンセミコンダクター、マレーシアのセレンバン)、300mm 径ウェハーに対応するようにウェハーソーとダイアタッチ設備が更新されています。さらに、以下の表に示すように、側面のメッキの改善とドライパックの廃止のため、ウェットブルフランクリードフレームの設計とメッキ工程が強化されています。</p> <p>オーダー可能な製品番号に変更はありません。</p> <p>本変更の結果として、製品マーキングに変更はありません。</p>

	変更前の表記	変更後の表記
ウェハー製造拠点	ON Aizu, Japan ON Gresham, US	<u>Global Foundries, US</u>
ウェハー径	200mm (existing sites)	300mm (Global Foundries)
ウェハープローブ拠点	ON Seremban, Malaysia	<u>Global Foundries, US</u>
バックグラインド、バックメタル拠点	ON ISMF, Malaysia	<u>Global Foundries, US</u>
ウェットブルフランクメッキ拠点	Metek, Malaysia (Sub-con)	ON Seremban, Malaysia
S08FL リードフレーム設計	<ol style="list-style-type: none"> 1. ゲートとソースリードに接続するタイパーはありません 2. アップセットリード設計 3. 標準のフラグサイズ 	<ol style="list-style-type: none"> 1. ゲートとソースリードに接続する追加のタイパー 2. フラットリード設計 3. フラグサイズを大きくする 
S08FL ケースアウトライン	488AA	507BA
S08FL ケースアウトラインの寸法 "L1"	0.125mm	0.15mm
u8FL リードフレーム設計	<ol style="list-style-type: none"> 1. ゲートとソースリードに接続するタイパーはありません 2. 面取りフラグ 	<ol style="list-style-type: none"> 1. ゲートとソースリードに接続する追加のタイパー 2. 面取りを削除しました 
u8FL ケースアウトライン	511AB	515AN
u8FL ケースアウトラインの寸法 "L"	0.30mm – 0.56mm	0.30mm – 0.59mm
側面めっき方法	Electroless SN plating	Electrolytic SN plating
梱包	Drypack (MSL 1)	No Drypack (MSL 1)
変更の理由 / 動機:	ソース/供給/能力変更プロセス/材料変更	
適合性、形状、機能、信頼性、製品安全性、または製造可能性に関して見込まれる影響	<p>製品は同じ製品仕様に基づいて認定および検証されています。製品は認定試験に正常に合格しています。潜在的な影響が確認される可能性があります。オン・セミコンダクターが PCN に関して実施する検査により、関連するリスクは検証および排除されます。</p> <p>予想される影響はありません。</p>	



影響を受ける拠点:

オン・セミコンダクター拠点:

On Semiconductor Gresham, United States

ON Semiconductor Aizu, Japan

ON Semiconductor Seremban, Malaysia

ON ISMF, Malaysia

外部製造工場 / 下請業者拠点:

GlobalFoundries, Fab 10, New York, US

Metek Seremban, Malaysia (Subcon)

部品の表示 / 変更の追跡可能性:

材料はオンのトレースコードとトラッキングにてトレースできます。

信頼性データの要約:

デバイス名: (DIE QUAL): NVMF55C404NL

RMS: 66099,67744,67566,67567

パッケージ: SO8FL-HE

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	Ta=175°C, 100% max rated Vds	2016 hrs	0/231
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	2016 hrs	0/231
HTSL	JESD22-A103	Ta= 175°C	2016 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off =2 min	30000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260°C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30

デバイス名: (PACKAGE QUAL): NVMF55C404N

RMS : 68528, 68531

パッケージ: SO8FL-HE

テスト	仕様	条件	間隔	結果
HTSL	JESD22-A103	Ta = 150 °C	1008 hrs	0/84
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/80
HTRB	JESD22-A108	Ta=150°C, 100% max rated Vds	1008 hrs	0/84
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	2016 hrs	0/84
TC+PC	JESD22-A104	Ta = -65°C to +150°C	1000 cyc	0/84
IOL+PC	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=100°C max, Ton = Toff = 2min	30000 cyc	0/84
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/504
RSH	JESD22-B106	Ta = 265°C, 10 sec		0/15
SD	JSTD002	Ta = 245°C, 10 sec		0/15



デバイス名(DIE QUAL): NVMF55C404N

RMS : 66100

パッケージ : SO8FL-HE

テスト	仕様	条件	間隔	結果
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	2016 hrs	0/231

デバイス名: (PACKAGE QUAL): NVTF56H850N

RMS : 64634,65635,65199,64753,66669

パッケージ : u8FL

テスト	仕様	条件	間隔	結果
HTSL	JESD22-A103	Ta = 175 °C	2016 hrs	0/231
HAST	JESD22 A110	130°C/85% RH ~18.8 psig, bias = 80% of rated V or up to maximum 100V	192 hrs	0/231
TC+PC	JESD22-A104	Ta = -55°C to +150°C	1000 cyc	0/231
UHASt	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
IOL+PC	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=100°C max, Ton = Toff = 2min	30000 cyc	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/924
RSH	JESD22-B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45

注 : AEC 1 ページャを添付しています。

添付文書を見るには:

1. ご使用のコンピューターに PDF 版の PCN をダウンロードします。
2. ダウンロードした PDF 版の PCN を開きます。
3. 添付欄を見るには、画面左 / 下部分のメニュー上にあるクリップ アイコンをクリックしてください。
4. 添付ファイルをクリックします

電気的特性の要約:

電気的特性への影響はありません。

影響を受ける部品の一覧:

注: 標準の部品番号(既製品)のみが部品一覧に記載されます。本 PCN に影響を受けるカスタム 部品は、PCN メールのお客様の特定の PCN の付属文書、または PCN カスタマイズポータルに記載されています。

現在の部品番号	新部品番号	認定試験用ピークル
NVMF55C404NWF3G	NA	NVMF55C404NLT1G, NVMF55C404NWF3G-K, NVTF56H850NWF3G



NVMF55C423NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C450NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C456NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C456NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C01NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C01NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C03NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C03NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C05NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF54C302NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C404NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG



NVMF55C404NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C404NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C404NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C404NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C410NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C423NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C423NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C423NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C426NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG



NVMF55C426NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C426NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C426NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C430NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG
NVMF55C442NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTF56H850NWFTAG



NVMF55C450NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C450NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C456NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVMF55C460NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS4C05NWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS4C13NWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVTFS6H850NWFTAG



NVTFS4C13NWFTWG	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS5C453NLWFTAG	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG
NVTFS5C466NLWFTAG	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NVMFS4C05NWFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVMFS5C404NLWFAFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVMFS5C404NLWFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVMFS5C430NWFAFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVMFS5C450NLWFAFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVMFS5C456NLWFAFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVMFS5C460NLWFAFT1G		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVTFS4C05NWFTAG		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVTFS5C453NLWFTAG		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	
NVTFS5C466NLWFTAG		NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVTFS6H850NWFTAG	NA	